Carrier-COMe-T6-E10
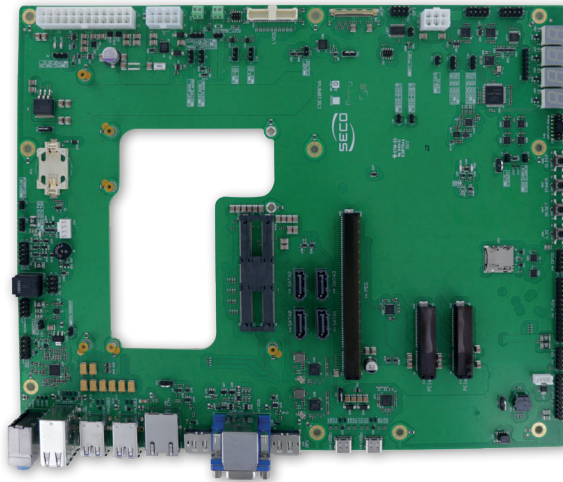Carrier Board for COM-Express® Rel. 3.1 Type 6 Modules for Development

Connectivity and Flexibility to Accelerate Development

HIGHLIGHTS

· COM Express 3.1 Type 6 Carrier board
· ATX form factor
· Especially suited for development and debugging of COM express modules
· Separated power supply for COM Express module and carrier board

CROSS PLATFORM *Philosophy*

FEATURES

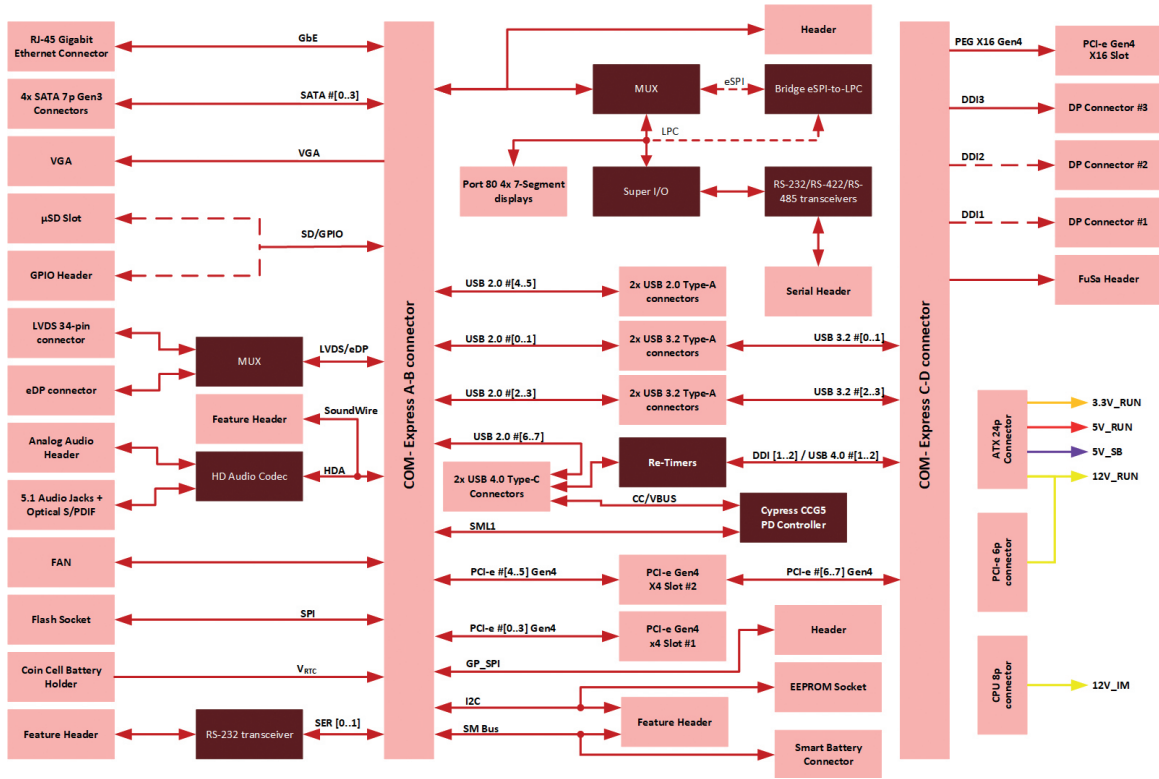|			
Video Interfaces	3 x DP++ connectors or 1 x DP++ connector and 2 x USB4.0 Type-C with Alternate-Mode VGA connector LVDS 24-bit Single/Dual Channel eDP 4-lanes 40 poles VESA connector Backlight control + LCD selectable voltages dedicated connector LVDS External EDID flash socket	**Other Interfaces**	4 x GPI + 4 x GPO pin header (interface multiplexed with µSD slot) SPI Flash Socket Button / LEDs front panel header 4-pin tachometric FAN connector I2C + SM Bus on feature Pin header I2C Flash Socket SM Bus Smart Battery Connector 4 x 7-segment LCD displays for POST codes LPC/eSPI internal header
Mass Storage	4x S-ATA 7p M connectors µSD Card slot (interface multiplexed with GPIO header)		
Networking	1x GbEthernet RJ-45 connector	**Power Supply**	ATX 24 poles connector for carrier board working only Auxiliary 12V connector for carrier board working only 12 VDC power in connector for COM Express module's working Cabled Coin-cell connector for RTC
PCI-e	2x PCI-e x4 Slots Gen4 1x PCI-e x16 Slot Gen4		
USB	2 x USB 4.0 on Type-C sockets with Alternate-Mode (factory alternative to 2 x DP++ and 2 x USB 2.0) 4 x USB 3.2 Host ports on Type-A sockets 4 x USB 2.0 Host ports on Quad Type-A sockets	**Operating Temperature***	0°C ÷ +60°C (Commercial version)
		Dimensions	305x244mm (ATXform factor, 12" x 9.6")
Audio	On-board HD Audio Codec (Realtek ALC888S) 5.1 Audio Jack with S/PDIF Optical interface Mic In + Line Out internal pin header		
Serial Ports	2 x RS-232 / RS-422 / RS-485 ports on internal pin header (from carrier board's LPC Dual UART controller) 2 x RS-232 ports on dedicated pin header (from module)		

*All carrier board components must remain within the operating temperature at any and all times, including start-up; carrier operating temperature is independent of the module installed. Please refer to the specific module for more details. Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.

BLOCK DIAGRAM

Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

DATA ORCHESTRATION

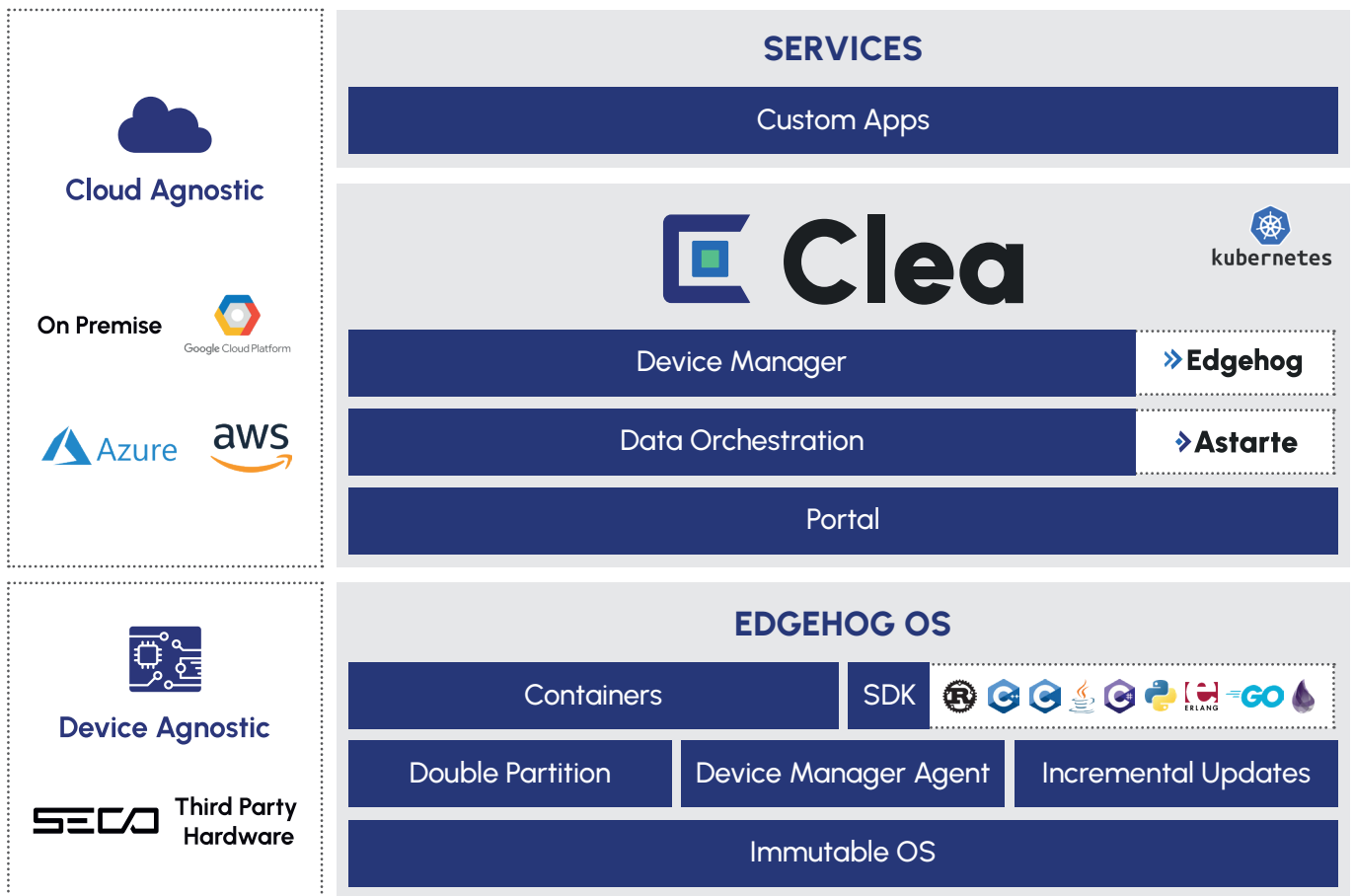Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.

Cloud Agnostic

On Premise
Google Cloud Platform

Azure   aws

Device Agnostic

SECO   Third Party Hardware

SERVICES

Custom Apps

Clea   kubernetes

Device Manager   » Edgehog

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